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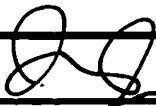
Substitute for form 1462A/PTO <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> (Use as many sheets as necessary)	Complete if Known	
	Application Number	10/808,192
	Filing Date	March 24, 2004
	First Named Inventor	Suh, Daewoong
	Group Art Unit	2841
	Examiner Name	Vigushin, John
Sheet 1 of 1		Attorney Docket No: 884.C25US1

US PATENT DOCUMENTS				
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date if Appropriate

FOREIGN PATENT DOCUMENTS				
Examiner Initial*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T <sup>2</sup>

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS				
Examiner Initial*	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.		T <sup>4</sup>
		ROMAN, JOHN W., et al., "Low Stress Die Attach by Low Temperature Transient Liquid Phase Bonding", <u>The International Society for Hybrid Microelectronics (ISHM) Symposium Proceedings, October 1992, (October 1992), 1-6</u>		

EXAMINER



DATE CONSIDERED

11/12/06